

MATERIAL DECLARATION SHEET



Material Number	SF-0603SP-M			
Product Line	Lead Free Multilayer Time Lag Chip Fuse			
Compliance Date	08/30/2017			
RoHS Compliant	YES	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Body	Glass Ceramic	1.5860	Boron	7440-42-8	7.39%	5.3455%	72.337%
				Carbon	7440-44-0	2.11%	1.5261%	
				Aluminum	7429-90-5	18.65%	13.4915%	
				Silicon	7440-21-3	15.24%	11.0240%	
				Potassium	7440-09-7	0.53%	0.3834%	
				Oxygen	7782-44-7	56.08%	40.5658%	
2	Termination	Silver with Glass	0.3838	Silver	7440-22-4	92.25%	16.1505%	17.505%
				Oxygen	7782-44-7	2.23%	0.3904%	
				Zinc	7440-66-6	1.64%	0.2871%	
				Silicon	7440-21-3	0.10%	0.0175%	
				Bismuth	7440-69-9	3.78%	0.6618%	
3	Fuse Link	Silver	0.0094	Silver	7440-22-4	100%	0.3559%	0.429%
4	Plating	Nickel	0.2100	Nickel	7440-02-0	100.00%	4.3020%	9.578%
		Tin		Tin	7440-31-5	100.00%	5.2771%	
				Oxygen	7782-44-7	50.86%	0.0435%	
				Aluminum	7429-90-5	16.02%	0.0137%	
				Silicon	7440-21-3	18.74%	0.0160%	
				Potassium	7440-09-7	0.57%	0.0005%	

MATERIAL DECLARATION SHEET



				Zinc	7440-66-6	9.82%	0.0084%	
				Iron	7439-89-6	3.99%	0.0034%	
6	Masking Layer	Glass Ceramic	0.0014	Boron	7440-42-8	9.83%	0.0063%	0.064%
				Carbon	7440-44-0	1.81%	0.0012%	
				Aluminum	7429-90-5	16.85%	0.0108%	
				Silicon	7440-21-3	15.58%	0.0100%	
				Potassium	7440-09-7	0.53%	0.0003%	
				Oxygen	7782-44-7	55.40%	0.0355%	
				Total weight	2.1925			

This Document was updated on: 8-30-17

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.